



Customer No.: 31561  
Docket No. 10320-US-PA  
Application No.: 10/605,012

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Applicant : Hung  
Application No. : 10/605,012  
Filed : 2003/9/1  
For : STRUCTURE OF FLIP CHIP PACKAGE WITH AREA  
BUMP  
Art Unit : 2812  
Examiner : ROMAN, ANGEL

**TRANSMITTAL LETTER**

002-1-703-746-4000

(Via fax: 1+4 pages)

Assistant Commissioner for Patents  
Arlington, Virginia 22202

Dear Sir,

In response to the Notice of Allowance and Fee(s) due, dated July 22, 2004, transmitted herewith please find the Issue Fee Transmittal (PTOL-85B) in duplicate.

Enclosed herewith please find two sheets of corrected drawing in reply to the requirement made in the Office Action dated February 20, 2004.

Please charge the fee in the amount of \$1679.00 for Issue Fee, Publication Fee and 3 soft copies to Account No. 50-2620 (Order No.: 10320-US-PA).

Thank you for your assistance in the subject matter. If you have any questions, please feel free to contact me.

Respectfully Submitted,  
JIANQ CHYUN Intellectual Property Office

Date:

By:

Belinda Lee  
Registration No.: 46,863

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